

**PRELIMINARY MEETING AGENDA –  
CE-2.2 SUBCOMMITTEE ON CONNECTORS AND SOCKETS  
(WAS SUBCOMMITTEES CE-2.2, 2.3, 2.4 AND 2.9)  
16 - 17 April 2007 in SAN DIEGO, CA.**

**1. Approval of the 28 – 29 September 2006 Minutes**

**2. SPECIFICATIONS BY PROJECT NUMBERS**

**"If any SP listed below receives insufficient votes for approval, the committee may approve the document for EDEC ballot at this meeting. It is the responsibility of the member to submit comments in writing prior to the meeting".**

**2. SPECIFICATIONS BY PROJECT NUMBERS**

A. SP-4965: Rev. EIA-540B0AE: Detail Land Grid Array (Contech Research is sponsor)

To be reviewed when EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets is developed.

B. SP-4970: EIA-540DAAA-A: Detail, DIP

It was reported that the specification is at EDEC for approval.

C. SP-4971: EIA-700A0AB: 68-pin Memory Card Connector

It was reported that the specification is at EDEC for approval.

D. SP-4973: EIA-540B0AB: Low Pin Count BGA

To be reviewed when EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets is developed.

E. SP-4982-1: EIA-5400000A: Generic

Carl reported that a second letter was sent to EIA for EDEC ballot (mccwil268) on 14 August 2006.

- Published as reaffirmed 1 March 2007. Received FedEx 15 March 2007.

F. SP-5058-A: EIA-720-A: Detail, SFF 2.5” Disk Drives

It was reported that the final ballot count from Cecelia Yates (EIA staff) on 15 August 2006 was 5 approvals now and 3 abstentions, and that a letter (mccwil272) was sent to Cecelia Yates (EIA Staff) for EDEC ballot on 15 August 2006.

- Standard published February 2007. Received FedEx 5 March 2007.

G. SP-5112 as follows:

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets
- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC
- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA
- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

It was reported that a second letter (mccwil269) was sent to Cecelia Yates (EIA Staff) EDEC ballot on 14 August 2006.

H. SP-5114 as follows:

- 540C000: Sectional Relay Sockets
- 540CA00: Blank, Relay Sockets
- 540CAAA: Detail, 10A Relay Socket
- 540CAAB: Detail, 5A Relay Socket

It was reported that a second letter (mccwil269) was sent to Cecelia Yates (EIA Staff) EDEC ballot on 14 August 2006.

- Published as reaffirmed 1 March 2007. Received FedEx 15 March 2007.

I. PN-5123, EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets (Contech Research, Tom Peel)

Draft dated 5 October 2005 sent to working group on 4 October 2006.

### **3. SPECIFICATIONS AWAITING PROJECT NUMBERS**

### **4. NEW BUSINESS**

Prepared by

Carl Fritz, Facilitator, CE-2.9